IEC QUALITY ASSESSMENT SYSTEM (IECQ)
covering Electronic Components,
Assemblies, Related Materials and Processes
For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S **Rev No.:** 5 **Revision Date:** 2021/06/07 **Page** 1 **of** 2

Board Types:	Rigid Multilayer (Type 4)		IPC 6012E Class 3*
	Rigid double-sided with plated through holes (Type 2)		
	Rigid single & double-sided with plain holes (Types 1 & 2) Double-Sided boards (Type 2) Single-Sided Boards (Type 1 & 2)		
	Flex-Rigid multilayer with through holes (Type 4)		IPC 6013D Class 3*
Base Materials:	Epoxide Woven Glass (IPC 4101, IPC 4202, IPC 4203, BS 4584) Polyimide film/polyester film (IPC 4204) Polytetrafluorethylene (IPC 4103)		
Board Size:	495.30 mm x 419.10 mm	single/double and multilayer	
	261.87 mm x 322.33 mm	flex-rigid multilayer	
Number of Layers:	32 maximum	Rigid multilayer	
	10 maximum	Flex-Rigid multilayer	
Conductors:	0.10 mm (photomech)	Tolerance -0.02 +0.03 mm	
Plated-through Hole Diameter:	0.20 mm	Minimum	Finished hole size
	0.80 mm	Minimum	Finished hole size
Aspect Ratio:	20 : 1	Maximum	single and double sided
	16.0 : 1	Maximum	multilayer
	2.27 : 1	Maximum	flex-rigid multilayer

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Finishes: *
Hot Air Solder Levelling
Immersion Silver
2.5µm Gold over Copper Edge Contacts
Liquid Photopolymer Solder Resist
Legend; UV or Oven Cured
Solder resist UV cured

Additional:
Selective Electroplated Nickel / Gold (2.5 µm) on Copper
Selective Electroless Nickel / Gold (0.05 µm) on Copper
Immersion Silver, Organic Coating
Nema LI 1

* This finish meets the solderability requirements.